AMENDMENTS TO THE SPECIFICATION

- **Please amend the specification paragraph beginning at page 9, line 11, as follows:**

In one embodiment, the PCB substrate 10' may be composed of a carbon-impregnated material, such as a carbon-filled epoxy. In another embodiment, PCB substrate 10' is composed of a material, such as polyimide, which must be cured. Polyimide is a cross-linked monomer that is formed into a polymer through a thermal or ultraviolet light process. It has been shown that in a partially cured state, polyimide is conductive, but once fully cured, is non-conductive. In accordance with one embodiment, therefore, PCB substrate 10' is only partially cured prior to the spot-plating operation. Thereafter, curing is completed, rendering the substrate essentially non-conductive.

- **Please amend the Abstract as follows:**

A method and apparatus for electrolytic plating of selected areas of printed circuit board traces is disclosed. The method is characterized by its elimination of the need for plating bus bars and plating contacts on the printed circuit board to facilitate a spot-plating process. In one embodiment, a printed circuit board substrate is provided which is at least partially conductive, such that a plating voltage may be applied to any one or more points on the substrate during a spot plating operation. In another embodiment, the substrate material is initially partially conductive, but following the spot-plating operation, is subjected to a curing treatment or the like to cause degeneration of the substrate's conductivity. Carbon-impregnated polyimide, partially-cured polyimide, FR4 or FR5, with appropriate contaminants introduced therein are contemplated as materials suitable for a printed circuit board substrate in accordance with the invention. In another embodiment, the traces are first applied to the partially conductive substrate by an electroplating operation wherein an electroplating voltage is applied to the substrate such that the substrate itself serves as one terminal of the electroplating system.